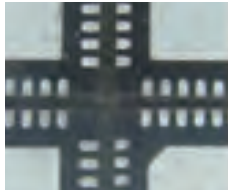
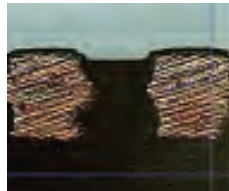




SELF-SHARPENING



QFN
50 mm/sec



QFN
50 mm/sec

Resin Bond Blade



Resin bond blade, with the characteristic of free-cutting and self-sharpening, can efficiently improve cut quality and efficiency on ductile and gummy materials such as QFNs and coppers and on hard-and-brittle materials such as glass and ceramics.

- Reduce copper burr and smear on ductile and gummy materials.
- Improve chipping, feed rate, and blade life on hard and brittle materials. Ultra thin blade (over 50um)

APPLICATION

QFNs, Glass for CIS Modules and Opticals, Ceramics, Quartz for Optical Fiber Communication, Splitter, IR-Cut Filter

SPECIFICATIONS

Suggested Max Spindle Speed: 35,000~40,000rpm Max Spindle Speed for Special Resin Bond Blade: 30,000rpm
Blade thickness 0.09~0.8mm depending on blade formulation

Tolerance /mm

SD	600	—	25	BA	56D	/	0.1T	/	40H
Grit Type	Grit Size		Concentration	Bond	OD		Thickness		ID
SD/SDC/CBN	02/06 #3000 04/08 #2000 05/10 #1500 06/12 #1200 08/16 #1000 10/20 #800 12/25 #700 20/30 #600 30/40 #500 40/60 #400 #325 #270 #230 #200 #170		25~100	BA/BB/BQ/BS	52~76.2 ±0.02		0.05~0.60 ±0.005~±0.020		40 H7
	um Mesh								

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Electro-formed Nickel Bond Blade

SGS



GOOD QUALITY
LOW WEAR RATE



EMCLED
80 mm/sec



HPLED
40/60 DHT 15 mm/sec

Electro-formed Nickel bond blade, featured by ultra thin, high strength and stiffness, is extremely rigid. It can give high endurance and robust properties during cutting process while maintaining very low blade wearing rate.

- Sophisticated electro-formed technology
- A wide selection of bonds available for various kinds of workpieces.

APPLICATION

EMC LED, Chip LED, WLCSP, Compound, Silicon, Magnetics, Ceramics, Materials required ultra thin blade.

SPECIFICATIONS

Max Spindle Speed: 37,000~38,000rpm
Blade thickness 0.025~0.3mm depending on blade formulation

Tolerance / mm

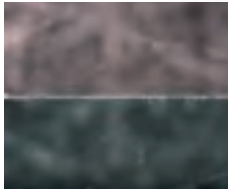
20/30	AA	56D	0.1T	40H	1w	2d	16N
Grit Size	Bond	OD	Thickness	ID	Slit Width	Slit Depth	No. of Slit
01/03 #5000 02/04 #4000 02/06 #3000 04/06 #2500 04/08 #2000 05/10 #1500 06/12 #1200 08/16 #1000 08/20 #900 10/20 #800 12/25 #700 20/30 #600 30/40 #500 40/60 #400 #325 um Mesh	DM <i>Soft</i> FB BB AA <i>Hard</i>	49~115 +0.05	0.025~0.25 <0.3 ±0.01 <0.1 ±0.005 <0.04 ±0.003	25.4/40/88.9 H6/H7	0.5mm 1mm 2mm 5mm	1mm 2mm	8N 16N 32N 64N

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Metal Bond Blade



**HIGH STIFFNESS
LONG BLADE LIFE**



Glass
5 mm/sec



Phosphor Film/Sheet
100 mm/sec

Metal bond blade, sintered and mold pressed under high temp. and pressure, has high rigidity and long blade life. With higher wear-resistance, balanced blade wearing profile, and higher stiffness, the metal bond blades can effectively reduce cutting defects such as slant cut and PKG size/profile issues while providing very long blade life.

- A wide selection of bonds available for various semiconductor packages such as BGAs as well as for glass and quartz cutting
- Ultra thin blade (over 45um).

APPLICATION

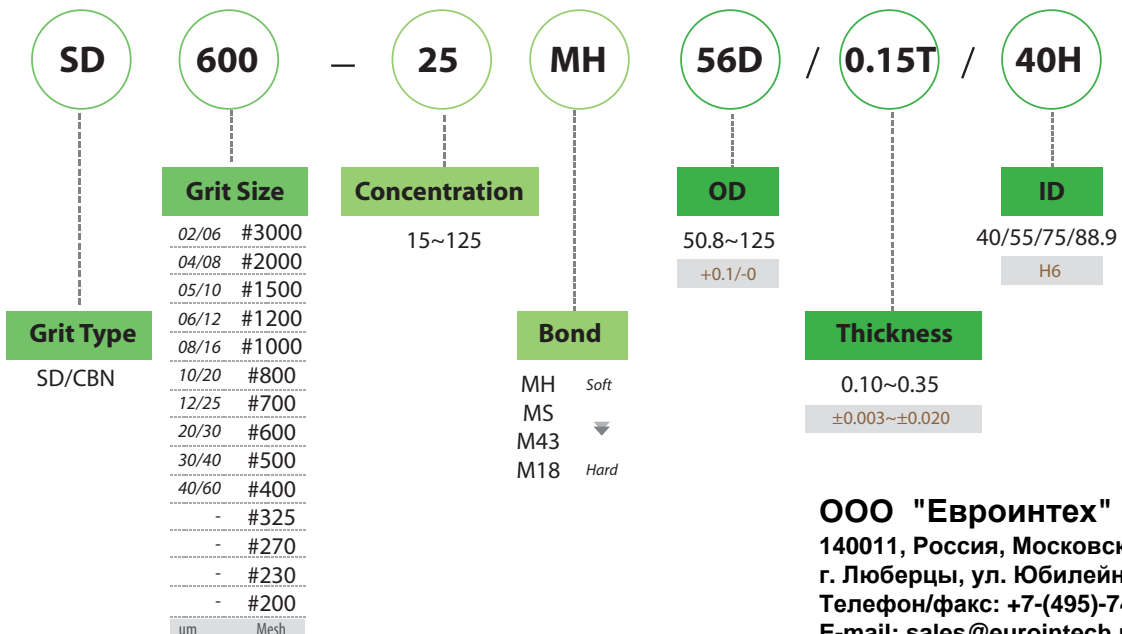
Sapphire, BGAs(BGA, LGA, CSP, SiP, MCP, EMMC, uSD card), Glass for CIS Modules and Opticals, Quartz, MLCC, Ceramics

SPECIFICATIONS

Max Spindle Speed: 40,000rpm

Blade thickness 0.075~0.35mm depending on blade formulation

Tolerance / mm



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Vitrified Bond Blade

Vitrified bond blade with high rigidity and cutting capability is able to keep the straightness on the entry and exit point and precision of work dimension during high-loading process. Consequently, this kind of blade realizes advanced machining on hard materials such as crystals and sapphires.

- Porous type.
- Realize high quality process on hard materials like Sapphire.

ELECTRICAL CONDUCTIVITY AVAILABLE



LED Chip on Board
6 mm/sec



PBGA Plastic Ball Grid Array Package
100 mm/sec

APPLICATION

Hard and Brittle Materials (Crystal, Sapphire, Ceramic)

SPECIFICATIONS

Max Spindle Speed: 30,000~32,000rpm

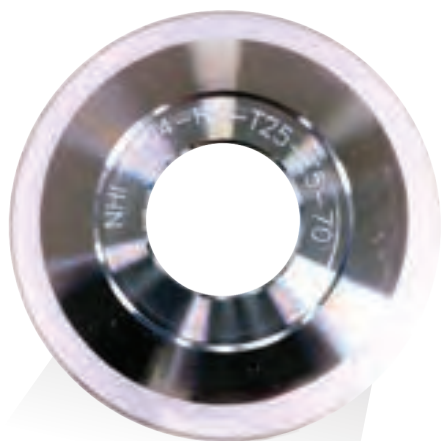
Blade thickness 0.01~1mm depending on blade formulation

Tolerance /mm

SD	600	J	25	N01	56D	0.15T	40H
Grit Type	Grit Size	Hardness	Concentration	Bond	OD	Thickness	ID
SD/CBN	02/06 #3000 04/08 #2000 05/10 #1500 06/12 #1200 08/16 #1000 10/20 #800 12/25 #700 20/30 #600 30/40 #500 40/60 #400 #325 #270 #230 #200 #170 um Mesh	G~S	25~125	N01~N10	49~125 ±0.02	0.07~0.6 ±0.003~±0.020	25.4/40/88.9 H7

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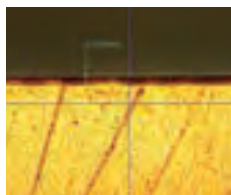
Hub Blade

Hub blade is applied on silicon wafer and compound semiconductor wafer cutting. Micrometer electro-formed technology provides higher process quality.

PRECISION CONTROL

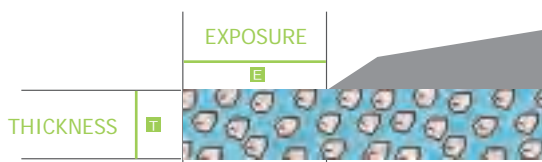


SIC
5 mm/sec



SIC
5 mm/sec

- Precise control of diamond distribution.
- Ultra high-speed separation filters for diamond grain in high precision.
- Well-proportioned diamond distribution on surface reduces back side chipping.



SPECIFICATIONS

0103	HH	L	08	20	P1
Grit Size	Bond	Concentration	Kerf	Exposure	Specials
0/3 0003	HS Soft	SL Super Low			
1/3 0103	HM Standard	L Low(Soft)			
2/4 0204	HH Hard	M Medium			
2/6 0206	HX Special	H Hard			
3/6 0305					
4/6 0406					
4/8 0408					
5/10 0510					
um					

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